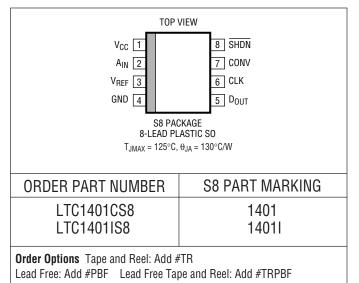
ABSOLUTE MAXIMUM RATINGS

PACKAGE/ORDER INFORMATION



Consult LTC Marketing for parts specified with wider operating temperature ranges.

Lead Free Part Marking: http://www.linear.com/leadfree/

POWER REQUIREMENTS The \bullet denotes specifications which apply over the full operating temperature range, unless otherwise noted specifications are at $T_A = 25^{\circ}C$. $V_{CC} = 3V$, $f_{SAMPLE} = 200kHz$, $t_r = t_f = 5ns$, unless otherwise specified.

SYMBOL	PARAMETER	CONDITIONS		MIN	TYP	MAX	UNITS
V_{CC}	Supply Voltage			2.7	3.0	3.6	V
I _{CC}	Supply Current	f _{SAMPLE} = 200ksps Nap Mode Sleep Mode Shutdown Mode	• • • •		5 0.5 6.5 4.5	10 1.0 15 10	mA mA μA μA
P _D	Power Dissipation	f _{SAMPLE} = 200ksps Nap Mode Sleep Mode Shutdown Mode	• • • •		15 1.5 19.5 13.5	30 3.0 45 30	mW mW μW μW

ANALOG INPUT The \bullet denotes specifications which apply over the full operating temperature range, unless otherwise noted specifications are at $T_A = 25^{\circ}C$. $V_{CC} = 3V$, $f_{SAMPLE} = 200kHz$, $t_r = t_f = 5ns$, unless otherwise specified.

SYMBOL	MBOL PARAMETER CONDITIONS		MIN	TYP	MAX	UNITS	
V_{IN}	Analog Input Range		•		0 to 2.048		V
I _{IN}	Analog Input Leakage Current	During Conversions (Hold Mode)	•			±1	μΑ
C _{IN}	Analog Input Capacitance	Between Conversions (Sample Mode) During Conversions (Hold Mode)			45 5		pF pF

INTERNAL REFERENCE CHARACTERISTICS The ullet denotes specifications which apply over the full operating temperature range, unless otherwise noted specifications are at $T_A = 25^{\circ}C$. $V_{CC} = 3V$, $f_{SAMPLE} = 200kHz$, $t_r = t_f = 5ns$, unless otherwise specified.

PARAMETER	CONDITIONS		MIN	TYP	MAX	UNITS
V _{REF} Output Voltage	I _{OUT} = 0		1.180	1.200	1.220	V
V _{REF} Output Tempco	I _{OUT} = 0	•		±10	±45	ppm/°C
V _{REF} Line Regulation	$2.7V \le V_{CC} \le 3.6V$			0.01		LSB/V
V _{REF} Load Regulation	$0 \le I_{OUT} \le 1 \text{mA}$			2		LSB/mA
V _{REF} Wake-Up Time from Sleep or Shutdown Mode	C _{VREF} = 10μF			3		ms
						1401fa



CONVERTER CHARACTERISTICS The \bullet denotes specifications which apply over the full operating temperature range, unless otherwise noted specifications are at $T_A = 25^{\circ}C$. With internal reference $V_{CC} = 3V$, $f_{SAMPLE} = 200kHz$, $t_r = t_f = 5ns$, unless otherwise specified.

PARAMETER	CONDITIONS		MIN	TYP	MAX	UNITS
Resolution (No Missing Codes)		•	12			Bits
Integral Linearity Error	(Note 6)	•			±1	LSB
Differential Linearity Error		•			±1	LSB
Offset Error		•			±6 ±8	LSB LSB
Full-Scale Error					±15	LSB
Full-Scale Tempco	I _{OUT(REF)} = 0	•		±10	±45	ppm/°C

DYNAMIC ACCURACY The ullet denotes specifications which apply over the full operating temperature range, unless otherwise noted specifications are at $T_A = 25^{\circ}C$. $V_{CC} = 3V$, $f_{SAMPLE} = 200$ kHz, $t_r = t_f = 5$ ns, unless otherwise specified.

SYMBOL	PARAMETER	CONDITIONS		MIN	TYP	MAX	UNITS
S/(N + D)	Signal-to-Noise Plus Distortion Ratio	50kHz Input Signal 100kHz Input Signal	•	65	68 65		dB dB
THD	Total Harmonic Distortion Up to 5th Harmonic	50kHz Input Signal 100kHz Input Signal	•		-72 -66	-65	dB dB
	Peak Harmonic or Spurious Noise	50kHz Input Signal 100kHz Input Signal	•		-74 -67	-65	dB dB
IMD	Intermodulation Distortion	f _{IN1} = 49.853kHz, f _{IN2} = 53.076kHz			-69		dB
	Full Power Bandwidth				2		MHz
	Full Linear Bandwidth $(S/(N + D) \ge 68dB)$				50		kHz

DIGITAL INPUTS AND OUTPUTS The • denotes specifications which apply over the full operating temperature range, unless otherwise noted specifications are at $T_A = 25^{\circ}C$. $V_{CC} = 3V$, $f_{SAMPLE} = 200kHz$, $t_r = t_f = 5ns$, unless otherwise specified.

SYMBOL	PARAMETER	CONDITIONS		MIN	TYP	MAX	UNITS
V_{IH}	High Level Input Voltage	V _{CC} = 3.6V	•	2.0			V
V _{IL}	Low Level Input Voltage	V _{CC} = 2.7V	•			0.8	V
I _{IN}	Digital Input Current	$V_{IN} = 0V \text{ to } V_{CC}$	•			±10	μА
C _{IN}	Digital Input Capacitance				5		pF
V _{OH}	High Level Output Voltage	$V_{CC} = 2.7V$, $I_0 = -10\mu A$ $V_{CC} = 2.7V$, $I_0 = -200\mu A$	•	2.40 2.25	2.64 2.50		V
V_{OL}	Low Level Output Voltage	$V_{CC} = 2.7V, I_0 = 400 \mu A$	•		0.13	0.4	V
I _{OZ}	Hi-Z Output Leakage D _{OUT}	V _{OUT} = 0V to V _{CC}	•			±10	μА
C_{0Z}	Hi-Z Output Capacitance D _{OUT}				15		pF
I _{SOURCE}	Output Source Current	V _{OUT} = 0V			-5		mA
I _{SINK}	Output Sink Current	$V_{OUT} = V_{CC}$			10		mA

TIMING CHARACTERISTICS The \bullet denotes specifications which apply over the full operating temperature range, unless otherwise noted specifications are at $T_A = 25^{\circ}C$. $V_{CC} = 3V$, $f_{SAMPLE} = 200kHz$, $t_r = t_f = 5ns$, unless otherwise specified.

SYMBOL	PARAMETER	CONDITIONS		MIN	TYP	MAX	UNITS
f _{SAMPLE(MAX)}	Maximum Sampling Frequency		•	200			kHz
t _{CONV}	Conversion Time	f _{CLK} = 3.2MHz	•			4.1	μS
t _{ACQ}	Acquisition Time				315		ns
f _{CLK}	CLK Frequency		•	0.1		3.2	MHz
t _{CLK}	CLK Pulse Width	(Notes 5 and 8)	•	60			ns
t _{WK(NAP)}	Time to Wake Up from Nap Mode				350		ns
t ₁	CLK Pulse Width to Return to Active Mode		•	60			ns
t ₂	CONV↑ to CLK↑ Setup Time		•	100			ns
t_3	CONV [↑] After Leading CLK [↑]		•	0			ns
t ₄	CONV Pulse Width	(Note 7)	•	50			ns
t ₅	Time from CLK↑to Sample Mode				80		ns
t ₆	Aperture Delay of Sample-and-Hold	Jitter < 50ps			45		ns
t ₇	Minimum Delay Between Conversion	(Note 5)	•		350	550	ns
t ₈	Delay Time, CLK↑ to D _{OUT} Valid	C _{LOAD} = 20pF	•		60	120	ns
t ₉	Delay Time, CLK↑to D _{OUT} Hi-Z	C _{LOAD} = 20pF	•		60	120	ns
t ₁₀	Time from Previous Data Remains Valid After CLK↑	C _{LOAD} = 20pF	•	15	50		ns
t ₁₁	Minimum Time Between Nap/Sleep Request to Wake Up Request	(Notes 5 and 8)	•	50			ns

Note 1: Stresses beyond those listed under Absolute Maximum Ratings may cause permanent damage to the device. Exposure to any Absolute Maximum Rating condition for extended periods may affect device reliability and lifetime.

Note 2: All voltage values are with respect to GND.

Note 3: When these pin voltages are taken below GND or above V_{CC} , they will be clamped by internal diodes. This product can handle input currents greater than 40mA without latch-up if the pin is driven below GND or above V_{CC}

Note 4: When these pin voltages are taken below GND, they will be clamped by internal diodes. This product can handle input currents greater than 40mA without latch-up if the pin is driven below GND. These pins are not clamped to V_{CC} .

Note 5: Guaranteed by design, not subject to test.

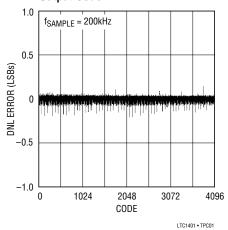
Note 6: Integral nonlinearity is defined as the deviation of a code from a straight line passing through the actual endpoints of the transfer curve. The deviation is measured from the center of the quantization band.

Note 7: The rising edge of CONV starts a conversion. If CONV returns low at a bit decision point during the conversion, it can create small errors. For best performance, ensure that CONV returns low either within 120ns after the conversion starts (i.e., before the first bit decision) or after the 14 clock cycles. (Figure 13 Timing Diagram).

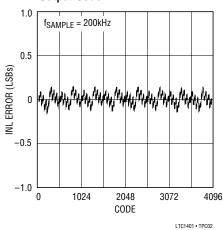
Note 8: If this timing specification is not met, the device may not respond to a request for a conversion. To recover from this condition a NAP request is required.

TYPICAL PERFORMANCE CHARACTERISTICS

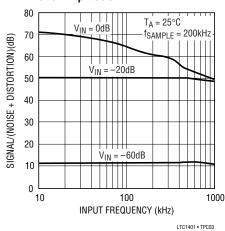
Differential Nonlinearity vs Output Code



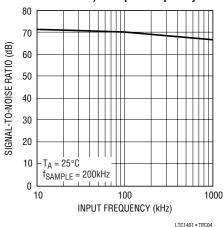
Integral Nonlinearity vs Output Code



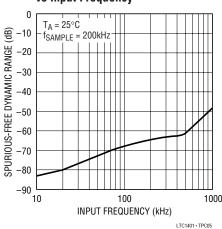
S/(N + D) vs Input Frequency and Amplitude



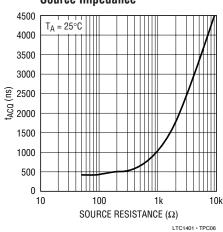
Signal-to-Noise Ratio (Without Harmonics) vs Input Frequency



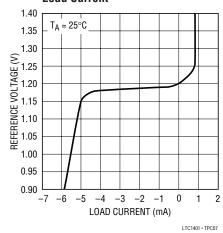
Peak Harmonic or Spurious Noise vs Input Frequency



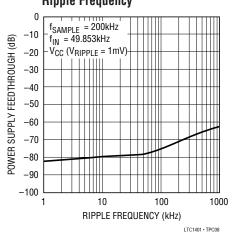
Acquisition Time vs Source Impedance



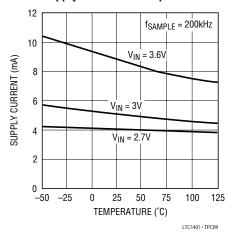
Reference Voltage vs Load Current



Power Supply Feedthrough vs Ripple Frequency



Supply Current vs Temperature



1401fa

PIN FUNCTIONS

 V_{CC} (Pin 1): Positive Supply, 3V. Bypass to GND (10μF tantalum in parallel with $0.1\mu F$ ceramic).

AIN (Pin 2): Analog Input. 0V to 2.048V.

 V_{REF} (**Pin 3**): 1.2V Reference Output. Bypass to GND (10 μ F tantalum in parallel with 0.1 μ F ceramic).

GND (Pin 4): Ground. GND should be tied directly to an analog ground plane.

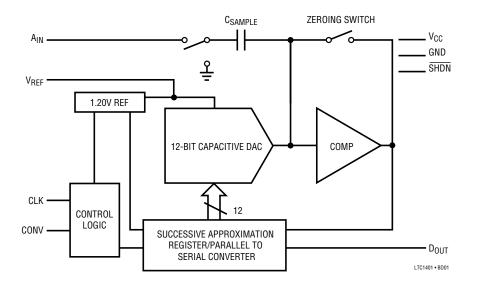
D_{OUT} (**Pin 5**): The A/D conversion result is shifted out from this pin.

CLK (Pin 6): Clock. This clock synchronizes the serial data transfer. A minimum CLK pulse of 60ns signals the ADC to wake up from Nap or Sleep mode.

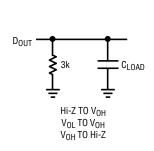
CONV (Pin 7): Conversion Start Signal. This active high signal starts a conversion on its rising edge. Keeping CLK low and pulsing CONV two/four times will put the ADC into Nap/Sleep mode.

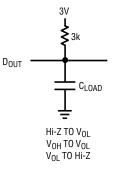
SHDN (Pin 8): Shutdown Input. Pull this pin Low to put the ADC in Shutdown mode and save power (REFRDY will go Low). The device will draw 4.5µA in this mode.

FUNCTIONAL BLOCK DIAGRAM



TEST CIRCUITS





LTC1401 • TC01

1401fa





Conversion Details

The LTC1401 uses a successive approximation algorithm and an internal sample-and-hold circuit to convert an analog signal to a 12-bit serial output based on a precision internal reference. The control logic provides an easy interface to microprocessors and DSPs through serial 3-wire connections.

A rising edge on the CONV input starts a conversion. At the start of a conversion the successive approximation register (SAR) is reset. Once a conversion cycle has begun, it cannot be restarted.

During conversion, the internal 12-bit capacitive DAC output is sequenced by the SAR from the most significant bit (MSB) to the least significant bit (LSB). Referring to Figure 1, the A_{IN} input connects to the sample-and-hold capacitor during the acquire phase and the comparator offset is nulled by the feedback switch. In this acquire phase, it typically takes 315ns for the sample-and-hold capacitor to acquire the analog signal. During the convert phase, the comparator feedback switch opens, putting the comparator into the compare mode. The input switches C_{SAMPLE} to ground, injecting the analog input charge onto the summing junction. This input charge is successively compared with the binary-weighted charges supplied by the capacitive DAC. Bit decisions are made by the high speed comparator. At the end of a conversion, the DAC

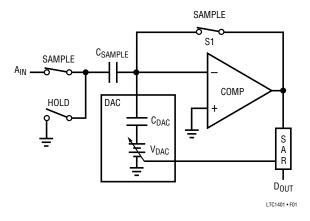


Figure 1. A_{IN} Input

output balances the A_{IN} input charge. The SAR contents (a 12-bit data word) which represent the input voltage, are presented through the serial pin D_{OLT} .

Dynamic Performance

The LTC1401 has excellent high speed sampling capability. FFT (Fast Fourier Transform) test techniques are used to test the ADC's frequency response, distortion and noise at the rated throughput. By applying a low distortion sine wave and analyzing the digital output using an FFT algorithm, the ADC's spectral content can be examined for frequencies outside the fundamental. Figure 2a shows a typical LTC1401 FFT plot.

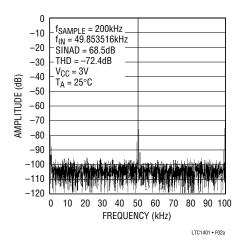


Figure 2a. LTC1401 Nonaveraged, 4096 Point FFT Plot with 50kHz Input Frequency

Signal-to-Noise Ratio

The signal-to-noise plus distortion ratio [S/(N+D)] is the ratio between the RMS amplitude of the fundamental input frequency to the RMS amplitude of all other frequency components at the A/D output. The output is band limited to frequencies from DC to half the sampling frequency. Figure 2a shows a typical spectral content with a 200kHz sampling rate and a 50kHz input. The dynamic performance is excellent for input frequencies up to the Nyquist limit of 100kHz as shown in Figure 2b.

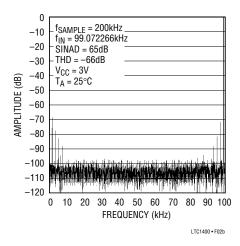


Figure 2b. LTC1401 Nonaveraged, 4096 Point FFT Plot with 100kHz Input Frequency

Effective Number of Bits

The effective number of bits (ENOBs) is a measurement of the effective resolution of an ADC and is directly related to the S/(N + D) by the equation:

$$N = \frac{S/(N+D) - 1.76}{6.02}$$

where N is the effective number of bits of resolution and S/(N + D) is expressed in dB. Figure 3 shows ENOBs vs Input Frequency.

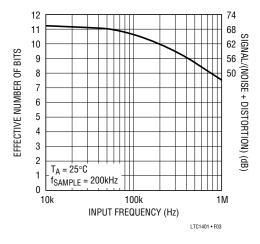


Figure 3. Effective Bits and Signal-to-Noise + Distortion vs Input Frequency

Total Harmonic Distortion

Total harmonic distortion (THD) is the ratio of the RMS sum of all harmonics of the input signal to the fundamental itself. The out-of-band harmonics alias into the frequency band between DC and half of the sampling frequency. THD is expressed as:

THD =
$$20\log \frac{\sqrt{V2^2 + V3^2 + ...Vn^2}}{V1}$$

Where V1 is the RMS amplitude of the fundamental frequency and V2 through Vn are the amplitudes of the second through nth harmonics. THD vs input frequency is shown in Figure 4. The LTC1401 has good distortion performance up to the Nyquist frequency and beyond.

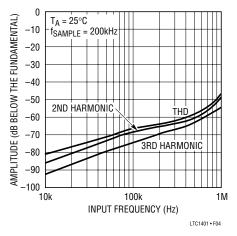


Figure 4. Distortion vs Input Frequency

Intermodulation Distortion

If the ADC input signal consists of more than one spectral component, the ADC transfer function nonlinearity can produce intermodulation distortion (IMD) in addition to THD. IMD is the change in one sinusoidal input caused by the presence of another sinusoidal input at a different frequency.

If two pure sine waves of frequencies fa and fb are applied to the ADC input, nonlinearities in the ADC transfer function can create distortion products at sum and differ-

LINEAR

ence frequencies of mfa \pm nfb, where m and n = 0, 1, 2, 3, etc. For example, the 2nd order IMD terms include (fa + fb) and (fa - fb) while 3rd order IMD terms includes (2fa + fb), (2fa - fb), (fa + 2fb) and (fa - 2fb). If the two input sine waves are equal in magnitude, the value (in decibels) of the 2nd order IMD products can be expressed by the following formula.

$$IMD(fa \pm fb) = 20log \frac{Amplitude at (fa \pm fb)}{Amplitude at fa}$$

Figure 5 shows the IMD performance at a 50kHz input.

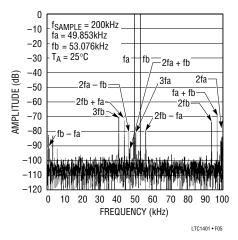


Figure 5. Intermodulation Distortion Plot

Peak Harmonic or Spurious Noise

The peak harmonic or spurious noise is the largest spectral component excluding the input signal and DC. This value is expressed in decibels relative to the RMS value of a full-scale input signal.

Full Power and Full Linear Bandwidth

The full power bandwidth is the input frequency at which the amplitude of the reconstructed fundamental is reduced by 3dB for a full-scale input signal.

The full linear bandwidth is the input frequency at which the S/(N+D) has dropped to 68dB (11 effective bits).

Driving the Analog Input

The analog input of the LTC1401 is easy to drive. It draws only one small current spike while charging the sample-and-hold capacitor at the end of a conversion. During conversion, the analog input draws only a small leakage current. The only requirement is that the amplifier driving the analog input must settle after the small current spike before the next conversion starts. Any op amp that settles in 315ns to small load current transients will allow maximum speed operation. If a slower op amp is used, more settling time can be provided by increasing the time between conversions. Suitable devices capable of driving the ADC's A_{IN} input include the LT®1498 and the LT1630 op amps.

The following list is a summary of the op amps that are suitable for driving the LTC1401, more detailed information is available in the Linear Technology databooks or the Linear Technology Web site.

LT1215/LT1216: Dual and quad 23MHz, $50V/\mu s$ single supply op amps. Single 5V to $\pm 15V$ supplies, 6.6mA specifications, 90ns settling to 0.5LSB.

LT1229/LT1230: Dual and quad 100MHz current feedback amplifiers. $\pm 2V$ to $\pm 15V$ supplies, 6mA supply current each amplifier. Low noise. Good AC specs.

LT1498/LT1499: Dual or quad 10MHz, $6V/\mu s$, single 2.2V to $\pm 15V$ supplies, 1.7mA supply current per amplifier, input/output swings rail-to-rail. Excellent AC and DC specs.

LT1630: Dual or quad 30MHz, $10V/\mu s$, single 2.7V to $\pm 15V$ supplies, 3.5mA supply current per amplifier, input/output swings rail-to-rail. Good AC and DC specs.

Internal Reference

The LTC1401 has an on-chip, temperature compensated, curvature corrected, bandgap reference, which is factory trimmed to 1.20V. It is internally connected to the DAC and

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is available at Pin 3 to provide up to 1mA current to an external load. For minimum code transition noise, the reference output should be decoupled with a capacitor to filter wideband noise from the reference ($10\mu F$ tantalum in parallel with a $0.1\mu F$ ceramic is recommended). The V_{REF} pin can be driven with a DAC or other means to provide input span adjustment. The V_{REF} pin must be driven to at least 1.25V to prevent conflict with the internal reference. The reference should not be driven to more than 3V.

Figure 6 shows an LT1360 op amp driving the reference pin. Figure 7 shows a typical reference (LT1634-1.25) connected to the LTC1401. This will provide improved drift (equal to the maximum 25ppm/°C of the LT1634-1.25) and a 2.1338V full scale.

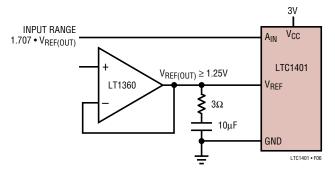


Figure 6. Driving the V_{REF} with the LT1360 Op Amp

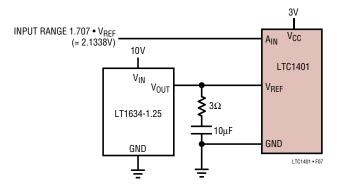


Figure 7. Supplying a 2.5V Reference Voltage to the LTC1401 with the LT1634-1.25

UNIPOLAR OPERATION AND ADJUSTMENT

Figure 8 shows the ideal input/output characteristics for the LTC1401. The code transitions occur midway between successive integer LSB values (i.e., 0.5LSB, 1.5LSB, 2.5LSB, ... FS - 1.5LSB). The output code is straight binary with 1LSB = 2.048V/4096 = 0.5mV.

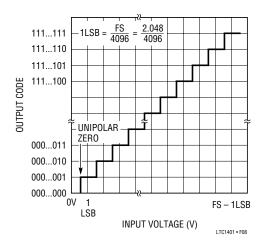


Figure 8. LTC1401 Unipolar Transfer Characteristics

Unipolar Offset and Full-Scale Error Adjustments

In applications where absolute accuracy is important, the offset and full-scale errors can be adjusted to zero. Offset error must be adjusted before full-scale error. Figure 9a shows the extra components required for full scale error adjustment. If both offset and full-scale adjustments are needed, the circuit in Figure 9b can be used. For zero offset error, apply 0.25mV (i.e., 0.5LSB) at the input and adjust the offset trim until the LTC1401 output code flickers between 0000 0000 0000 and 0000 0000 0001. For zero full-scale error, apply an analog input of 2.04725V (FS – 1.5LSB or last code transition) at the input and adjust R5 until the LTC1401 output code flickers between 1111 1111 1111.

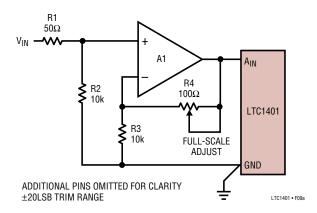


Figure 9a. LTC1401 Full-Scale Adjust Circuit

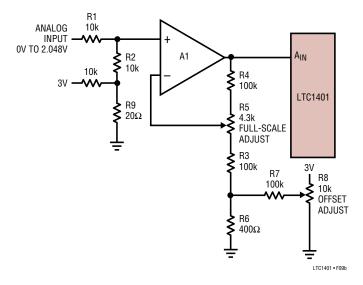


Figure 9b. LTC1401 Offset and Full-Scale Adjust Circuit

BOARD LAYOUT AND BYPASSING

Wire wrap boards are not recommended for high resolution or high speed A/D converters. To obtain the best performance from the LTC1401, a printed circuit board is required. Layout for the printed circuit board should ensure that digital and analog signal lines are separated as much as possible. In particular, care should be taken not to run any digital traces alongside an analog signal trace or underneath the ADC. The analog input should be screened by GND.

High quality tantalum and ceramic bypass capacitors should be used at the V_{CC} and V_{REF} pins as shown in the Typical Application on the first page of this datasheet. For

optimum performance, a $10\mu F$ surface mount AVX capacitor in parallel with a $0.1\mu F$ ceramic is recommended for the V_{CC} and V_{REF} pins. The capacitors must be located as close to the pins as possible. The traces connecting the pins and the bypass capacitors must be kept short and should be made as wide as possible.

Input signal leads to A_{IN} and signal return leads from GND (Pin 4) should be kept as short as possible to minimize noise coupling. In applications where this is not possible, a shielded cable between the analog input signal and the ADC is recommended. Also, any potential difference in grounds between the analog signal and the ADC appears as an error voltage in series with the analog input signal. Attention should be paid to reducing the ground circuit impedance as much as possible.

Figure 10 shows the recommended system ground connections. All analog circuitry grounds should be terminated at the LTC1401 GND pin. The ground return to the power supply from Pin 4 should be low impedance for noise free operation. Digital circuitry grounds must be connected to the digital supply common.

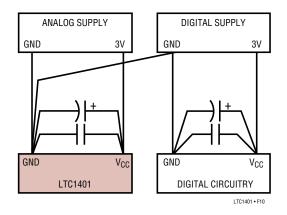


Figure 10. Power Supply Connection

Power-Down Mode

Upon power up, the LTC1401 is initialized to the active state and is ready for conversion. However, the chip can be easily placed into Nap or Sleep mode by exercising the right combination of CLK and CONV signals. In Nap mode, all power is off except the internal reference which remains active and provides 1.20V output voltage to the other



circuitry. In this mode, the ADC draws only 1.5mW of power instead of 15mW (for minimum power, the logic inputs must be within 500mV of the supply rails). The wake-up time from Nap mode to active mode is 350ns. In Sleep mode, power consumption is reduced to 19.5 μ W by cutting off the supply to the comparator and reference. Figure 11 illustrates power-down methods for the LTC1401. The chip enters Nap mode by keeping the CLK signal low and pulsing the CONV signal twice. For Sleep mode operation, CONV signal should be pulsed four times while CLK is kept low. NAP and SLEEP modes are activated on the falling edge of the CONV pulse. By pulling SHDN low, the LTC1401 enters Shutdown mode and power consumption drops to 13.5 μ W.

Once \overline{SHDN} goes high, the LTC1401 returns to active mode or the LTC1401 returns to active mode by pulsing the CLK signal if the device has entered Nap/Sleep mode. During the transistion from Sleep mode to active mode, the V_{REF} voltage ramp-up time is a function of its loading conditions. With a $10\mu F$ bypass capacitor, the wake-up time from Sleep mode is typically 3ms. A REFRDY signal is activated once the reference has settled and is ready for

an A/D conversion. This REFRDY bit is sent to the D_{OUT} pin as the first bit followed by the 12-bit data word (refer to Figure 12).

DIGITAL INTERFACE

The digital interface requires only three digital lines. CLK and CONV are both inputs, and the D_{OUT} output provides the conversion result in serial form.

Figures 12 and 13 show the digital timing waveform of the LTC1401 during the Analog to Digital Conversion. The CONV rising edge starts the conversion. Once initiated, it can not be restarted until the conversion is completed. If the time from the CONV signal to the CLK rising edge is less than t_2 , the digital output will be delayed by one clock cycle.

The digital output data is updated on the rising edge of the CLK line. The digital output data consists of a REFRDY bit followed by the valid 12-bit data word. D_{OUT} data should be captured by the receiving system on the rising CLK edge. Data remains valid for a minimum time of t_{10} after the rising CLK edge to allow capture to occur.

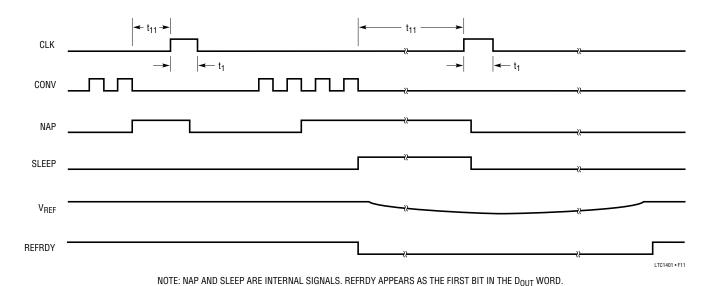


Figure 11. Nap Mode and Sleep Mode Waveforms

LINEAD TECHNOLOGY

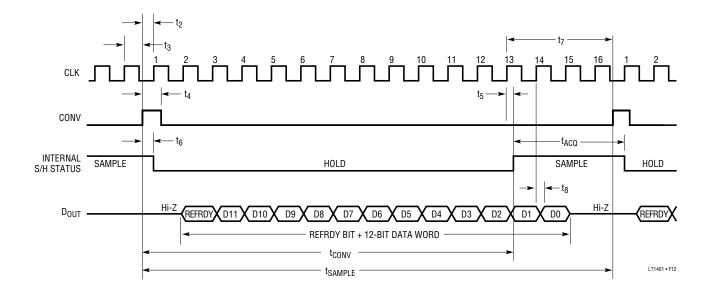


Figure 12. ADC Digital Timing Waveform

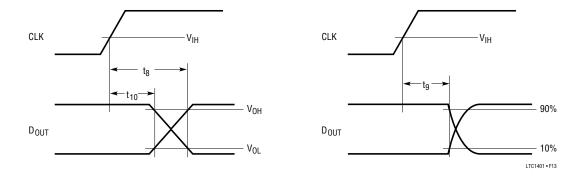
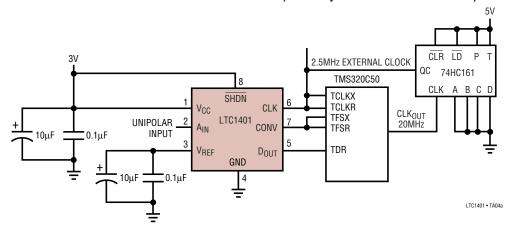
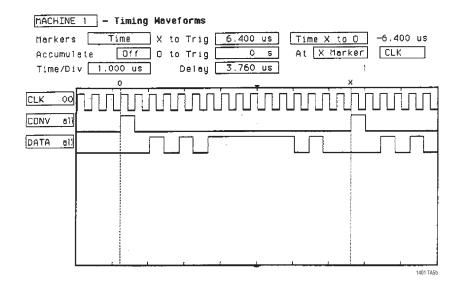


Figure 13. CLK to D_{OUT} Delay

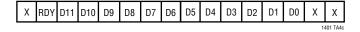




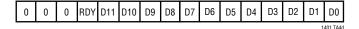
Logic Analyzer Waveforms Show 6.4 \(\mu \) Throughput Rate (Input Voltage = 0.765V, Output Code = 0101 1111 1010 = 1530 10)



Data from the LTC1401 Loaded into the TMS320C50's TRCV Register



Data Stored in the TMS320C50's Memory (in Right Justified Format)





TMS320C50 Code for Circuit

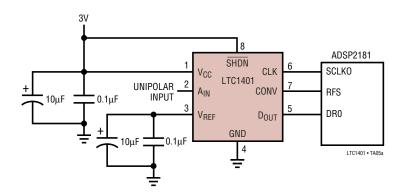
THIS PROGRAM DEMONSTRATES THE LTC1401 INTERFACE TO THE TMS320C50. FRAME SYNC PULSE IS GENERATED FROM TFSX. DATA SHIFT CLOCK IS DERIVED FROM CLKOUT.

```
*Initialization*
                                    ; Defines global symbolic names
    .mmregs
  - Initialized data memory to zero
                    0F00h
          .ds
                                    : Initialize data to zero
DATA0
          .word
                                     Begin sample data location
DATA1
          .word
                    0
                    0
DATA2
                                     Location of data
          .word
DATA3
                    0
          .word
DATA4
          .word
                    0
DATA5
          .word
                    0
                                    ; End sample data location
:- - Set up the ISR vector
                    080Ah
                                    ; Serial ports interrupts
          .ps
rint:
          B
                    RECEIVE
                                    ; 0A;
          В
                    TRANSMIT
                                    ; OC;
xint:
trnt:
          В
                    TREC
                                    ; 0E;
          В
                    TTRANX
txnt:
                                    ; 10;
;- - Setup the reset vector
   .ps 0A00h
   .entry
START:
*TMS320C50 Initialization*
   SETC INTM
                          : Temporarily disable all interrupts
   LDP #0
                           Set data page pointer to zero
   OPL #0834h, PMST
                          ; Set up the PMST status and control register
   LACC #0
   SAMM CWSR
                          : Set software wait state to 0
   SAMM PDWSR
*Configure Serial Port*
   SPLK #0028h, TSPC
                          : Set TDM Serial Port
                           TDM = 0 Stand Alone mode
                           ; DLB = 0 Not loop back
                           F0 = 0.16 Bits
                           ; FSM = 1 Burst Mode
                           MCM = 0 CLKR is generated externally
                           TXM = 1 FSX as output pin
                           Put serial port into reset
                           (XRST = RRST = 0)
   SPLK #00E8h, TSPC
                          ; Take Serial Port out of reset
                           (XRST = RRST = 1)
   SPLK #0FFFFh, IFR
                          ; Clear all the pending interrupts
```

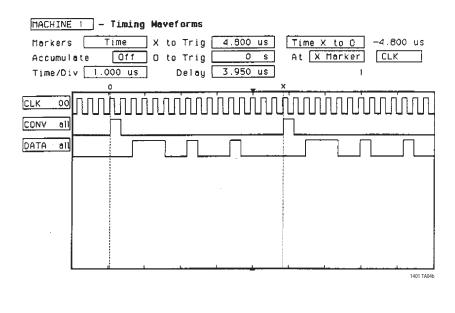
```
*Start Serial Communication*
   SACL TDXR
                         Generate frame sync pulse
   SPLK #040h, IMR
                         Turn on TRNT receiver interrupt
   CLRC INTM
                         Enable interrupt
   CLRC SXM
                         For Unipolar input, set for right shift
                         with no sign extension
   MAR
         *AR7
                         Load the auxiliary register pointer with seven
   LAR
         AR7, #0F00h
                         Load the auxiliary register seven with #0F00h
                         as the begin address for data storage
WAIT:
         NOP
                         Wait for a receive interrupt
         NOP
         NOP
   SACL TDXR
                         ; !! Regenerate the frame sync pulse
         WAIT
 ----;
*Receiver Interrupt Service Routine*
TREC:
   LAMM TRCV
                         : Load the data received from LTC1401
   SFR
                         Shift right two times
   SFR
                          ANDed with #1FFFh
   AND
         #1FFFh, 0
                         For converting the data to right
                         justified format
   SACL *+, 0
                          Write to data memory pointed by AR7 and
                         Increase the memory address by one
   LACC AR7
   SUB #0F05h.0
                          Compare to end sample address #0F05h
   BCND END TRCV, GEQ
                         If the end sample address has exceeded jump
                         to END TRCV
   SPLK #040h, IMR
                         Else re-enable the TRNT receive interrupt
   RETE
                         Return to main program and enable interrupt
*After Obtained the Data from LTC1401, Program Jump to END_TRCV*
END TRCV:
   SPLK #002h, IMR
                         ; Enable INT2 for program to halt
   CLRC INTM
SUCCESS:
         SUCCESS
*Fill the unused interrupt with RETE, to avoid program get "lost"*
TTRANX:
   RETE
RECEIVE:
   RETE
TRANSMIT:
   RETE
INIT2:
   B halt
                        ; Halts the running CPU
```



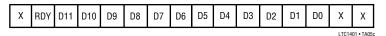
LTC1401 Interface to the ADSP2181's SPORTO (Frame Sync is Generated from RFS)



Logic Analyzer Waveforms Show 4.8µs Throughput Rate (Input Voltage = 1.604V, Output Code = 1100 1000 1000 = 3208₁₀)







Data Stored in the ADSP2181's Memory (Normal Mode, SLEN = D)

0	0	0	RDY	D11	D10	D9	D8	D7	D6	D5	D4	D3	D2	D1	D0
---	---	---	-----	-----	-----	----	----	----	----	----	----	----	----	----	----

LTC1401 • TA05d



ADSP2181 Code for Circuit

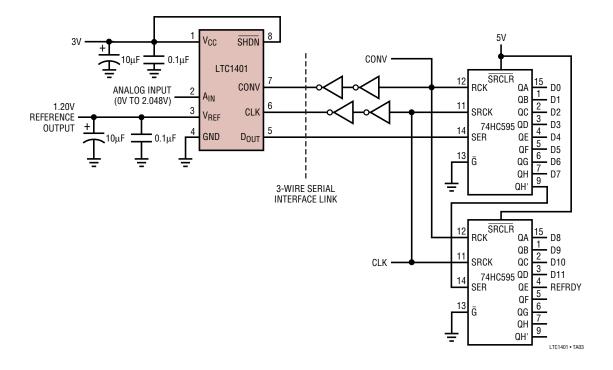
THIS PROGRAM DEMONSTRATES THE LTC1401 INTERFACE TO THE ADSP-2181. FRAME SYNC PULSE IS GENERATED FROM RFS. DATA SHIFT CLOCK IS INTERNALLY GENERATED.

```
/*Section 1: Initialization*/
.module/ram/abs = 0 adspltc; /*define the program module*/
   jump start;
                         /*jump over interrupt vectors*/
   nop; nop; nop;
                         /*code vectors here upon IRQ2 int*/
   rti: rti: rti: rti:
   rti; rti; rti; rti;
                         /*code vectors here upon IRQL1 int*/
   rti; rti; rti; rti;
                         /*code vectors here upon IRQL0 int*/
   rti; rti; rti; rti;
                         /*code vectors here upon SPORTO TX int*/
                         /*Section 5*/
   ax0 = rx0;
   dm (0x2000) = ax0; /*begin of SPORT0 receive interrupt*/
                         /*end of SPORT0 receive interrupt*/
   rti; rti; rti; rti;
                         /*code vectors here upon /IRQE int*/
                         /*code vectors here upon BDMA interrupt*/
   rti: rti: rti: rti:
   rti: rti: rti: rti:
                         /*code vectors here upon SPORT1 TX (IRQ1) int*/
                         /*code vectors here upon SPORT1 RX (IRQ0) int*/
   rti; rti; rti; rti;
                         /*code vectors here upon TIMER int*/
   rti; rti; rti; rti;
                         /*code vectors here upon POWER DOWN int*/
   rti; rti; rti; rti;
/*Section 2: Configure SPORTO*/
start:
/*to configure SPORT0 control reg*/
                         /*SPORT0 address = 0x3FF6*/
                         /*RFS is used for frame sync generation*/
                         /*RFS is internal, TFS is not used*/
                         /*bit 0-3 = Slen*/
                         /*F = 15 = 1111*/
                         /*E = 14 = 1110*/
                         /*D = 13 = 1101*/
                         /*bit 4,5 data type right justified zero filled MSB*/
                         /*bit 6 INVRFS = 0*/
                         /*bit 7 INVTFS = 0*/
                         /*bit 8 IRFS=1 receive internal frame sync*/
                         /*bit 9,10,11 are for TFS (don't care)*/
                         /*bit 12 RFSW=0 receive is normal mode*/
                         /*bit 13 RTFS=1 receive is framed mode*/
                         /*bit 14 ISCLK = 1 clock is internal*/
                         /*bit 15 multichannel mode = 0*/
   ax0 = 0x6F0D;
   dm (0x3FF6) = ax0;
```

```
/*Section 3: configure CLKDIV and RFSDIV, setup interrupts*/
/*to configure CLKDIV reg*/
   ax0 = 4;
   dm(0x3FF5) = ax0;
                        /*set the serial clock divide modulus reg
                        SCLKDIV*/
                        /*the input clock frequency = 16.67MHz*/
                        /*CLKOUT frequency = 2x = 33MHz*/
                        /*SCLK= 1/2*CLKOUT*1/(SCLKDIV+1)*/
                        /*for SCLKDIV = 4, SCLK = 33/10 = 3.3MHz*/
/*to Configure RFSDIV*
   ax0 = 15:
                        /*set the RFSDIV reg = 15*/
                        /*=> the frame sync pulse for every 16 SCLK*/
                        /*if frame sync pulse in every 15 SCLK, ax0=14*/
   dm(0x3FF4) = ax0;
/*to setup interrupt*/
   ifc= 0x0066;
                        /*clear any extraneous SPORT interrupts*/
                        /*IRQXB = level sensitivity*/
   icntl= 0;
                        /*disable nesting interrupt*/
                        /*bit 0 = timer int = 0*/
   imask= 0x0020:
                        /*bit 1 = SPORT1 or IRQ0B int = 0*/
                        /*bit 2 = SPORT1 or IRQ1B int = 0*/
                        /* bit 3 = BDMA int = 0*/
                        /*bit 4 = IRQEB int = 0*/
                        /*bit 5 = SPORT0 receive int = 1*/
                        /*bit 6 = SPORT0 transmit int = 0*/
                        /*bit 7 = IRQ2B int = 0*/
                        /*enable SPORT0 receive interrupt*/
/*Section 4: Configure System Control Register and Start Communication*/
/*to configure system control reg*/
   ax0 = dm(0x3FFF);
                          /*read the system control reg*/
   ay0 = 0xFFF0;
   ar = ax0 AND ay0;
                           /*set wait state to zero*/
   av0 = 0x1000:
   ar = ar OR ay0;
                           /*bit 12 = 1, enable SPORT0*/
   dm(0x3FFF) = ar;
/*frame sync pulse regenerated automatically*/
   cntr = 5000:
do waitloop until ce;
   nop;
   nop;
   nop;
   nop;
   nop;
   nop;
waitloop: nop;
   rts:
.endmod;
```



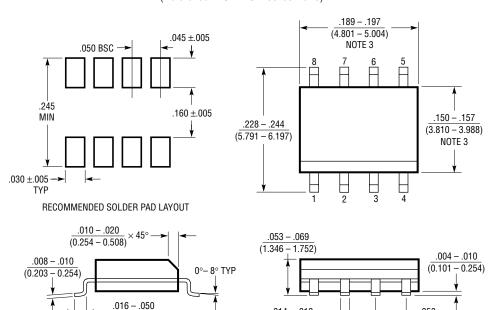
Quick Look Circuit for Converting Data to Parallel Format



PACKAGE DESCRIPTION

S8 Package 8-Lead Plastic Small Outline (Narrow .150 Inch)

(Reference LTC DWG # 05-08-1610)



.014 - .019

(0.355 – 0.483) TYP

NOTE:
1. DIMENSIONS IN (MILLIMETERS)

(0.406 - 1.270)

2. DRAWING NOT TO SCALE

3. THESE DIMENSIONS DO NOT INCLUDE MOLD FLASH OR PROTRUSIONS.
MOLD FLASH OR PROTRUSIONS SHALL NOT EXCEED .006" (0.15mm)

S08 0303

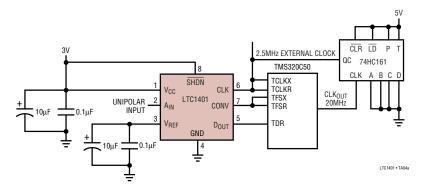
.050

(1.270)

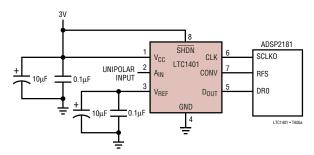
BSC



Interface to the TMS320C50's TDM Serial Port (Frame Sync is Generated from TFSX)



LTC1401 Interface to the ADSP2181's SPORTO (Frame Sync is Generated from RFS)



RELATED PARTS

PART NUMBER	DESCRIPTION	COMMENTS
LTC1285/LTC1288	12-Bit, 3V, 7.5/6.6ksps, Micropower Serial ADCs	0.48mW, 1-/2-Channel Input, SO-8
LTC1286/LTC1298	12-Bit, 5V, 12.5/11.16ksps, Micropower Serial ADCs	1.25mW, 1-/2-Channel Input, SO-8
LTC1290	12-Bit, 50ksps 8-Channel Serial ADC	5V or ±5V Input Range, 30mW, Full-Duplex
LTC1296	12-Bit, 46.5ksps 8-Channel Serial ADC	5V or ±5V Input Range, 30mW, Half-Duplex
LTC1403/LTC1403A	12-/14-Bit 2.8Msps Serial ADCs	3V, 15mW, MSOP-10 Package, Unipolar Input
LTC1403-1/LTC1403A-1	12-/14-Bit, 2.8Msps Serial ADCs	3V, 15mW, MSOP-10 Package, Bipolar Input
LTC1407/LTC1407A	12-/14-Bit, 3Msps Simultaneous Sampling ADCs	3V, 14mW, 2-Channel Unipolar Differential Inputs, MSOP-10
LTC1407-1/LTC1407A-1	12-/14-Bit, 3Msps Simultaneous Sampling ADCs	3V, 14mW, 2-Channel Bipolar Differential Inputs, MSOP-10
LTC1417	14-Bit, 400ksps Serial ADC	5V or ±5V, 20mW, Internal Reference, SSOP-16
LTC1609	16-Bit, 200ksps Serial ADC	5V, Configurable Bipolar or Unipolar Inputs to ±10V
LTC1860L/LTC1861L	12-Bit, 3V, 150ksps Serial ADCs	1.22mW, 1-/2-Channel Input, MSOP-8 and SO-8
LTC1860/LTC1861	12-Bit, 5V, 250ksps Serial ADCs	4.25mW, 1-/2-Channel Input, MSOP-8 and SO-8
LTC1864L/LTC1865L	16-Bit, 3V, 150ksps Serial ADCs	1.22mW, 1-/2-Channel Input, MSOP-8 and SO-8
LTC1864/LTC1865	16-Bit, 5V, 250ksps Serial ADCs	4.25mW, 1-/2-Channel Input, MSOP-8 and SO-8